Liverpool (Online), FCC physics workshop

# IDEA Preshower and Muon Detector

Status update and future plans

G Mezzadri (INFN Ferrara) on behalf of the working group

February 9, 2022



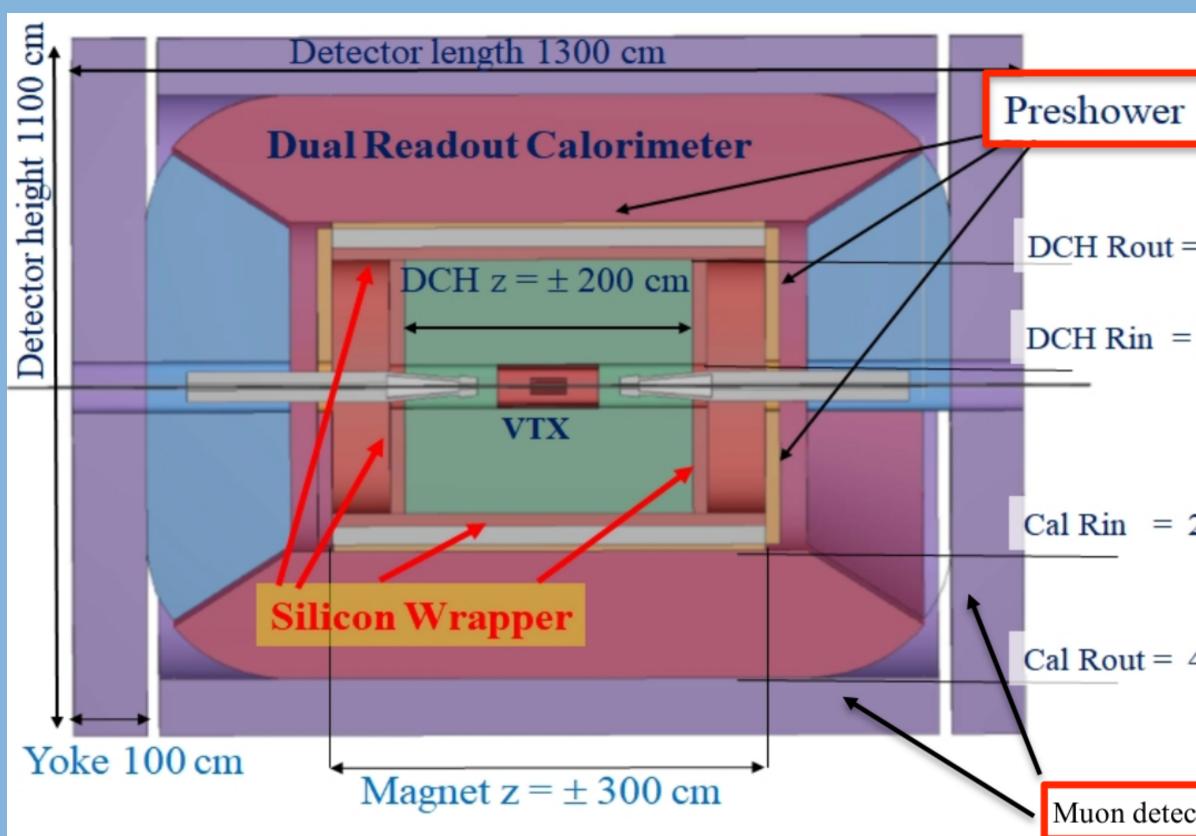


## IDEA Detector @ FCC-ee

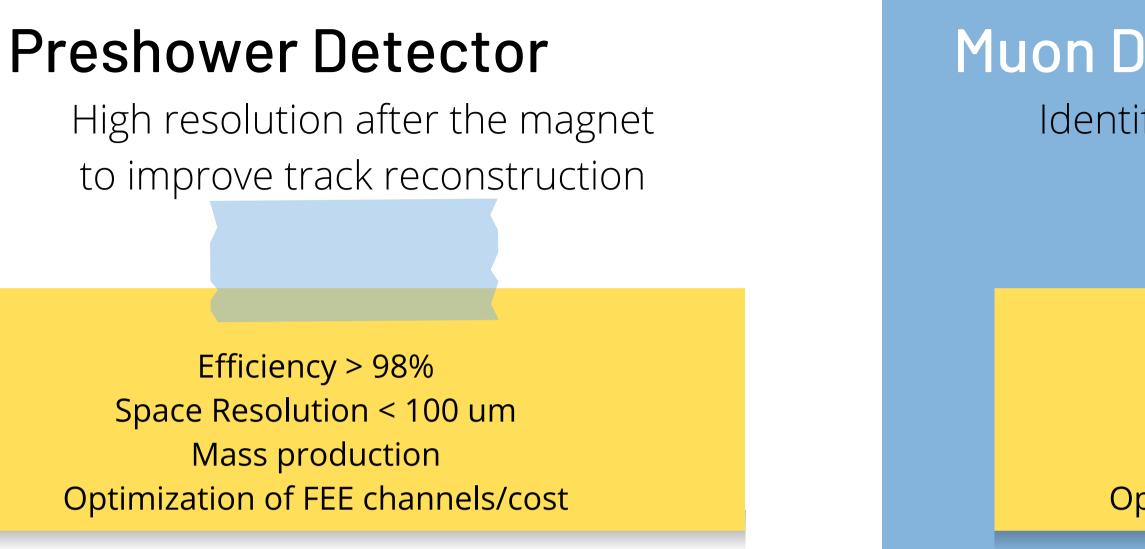
## **Pre Shower and Muon Detector**



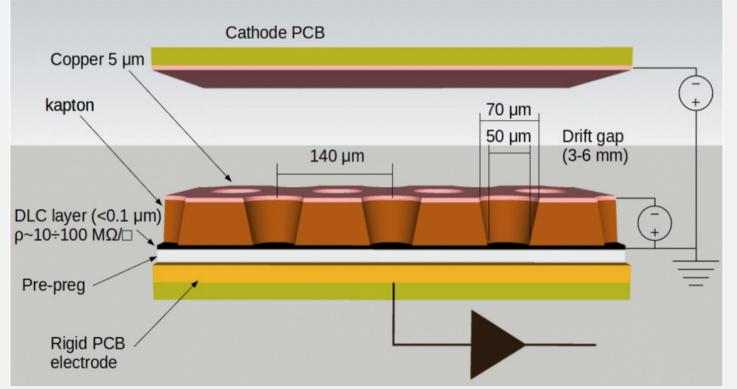
## **On going activities**



r	
t = 200  cm	
= 30 cm	IDEA
250 cm	Innovative Detector Electron-positror Accelerator
ector	



## micro-RWELL detector



## 50x50 cm<sup>2</sup> 2D tiles to cover more than 4330 m<sup>2</sup>

### Preshower

pitch = 0.4 mm FEE capacitance = 70 pF 1.5 million channels

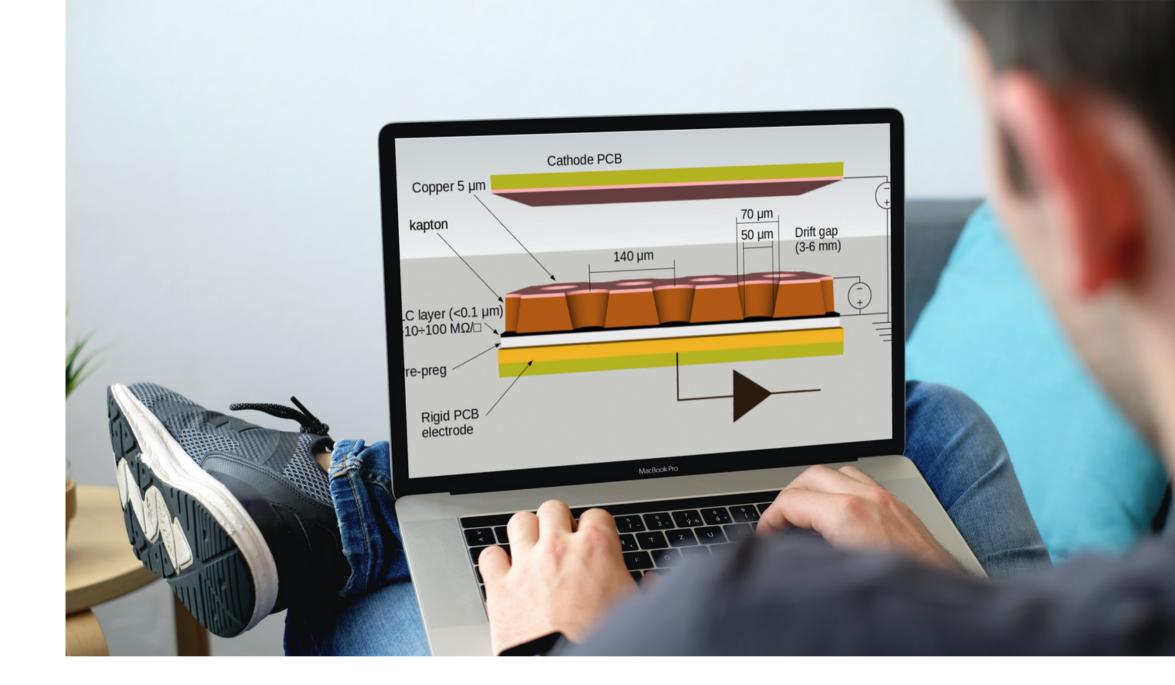
## **Muon Detector** Identify muons and search for LLP

### Efficiency > 98% Space Resolution < 400 um Mass production Optimization of FEE channels/cost

### Muon

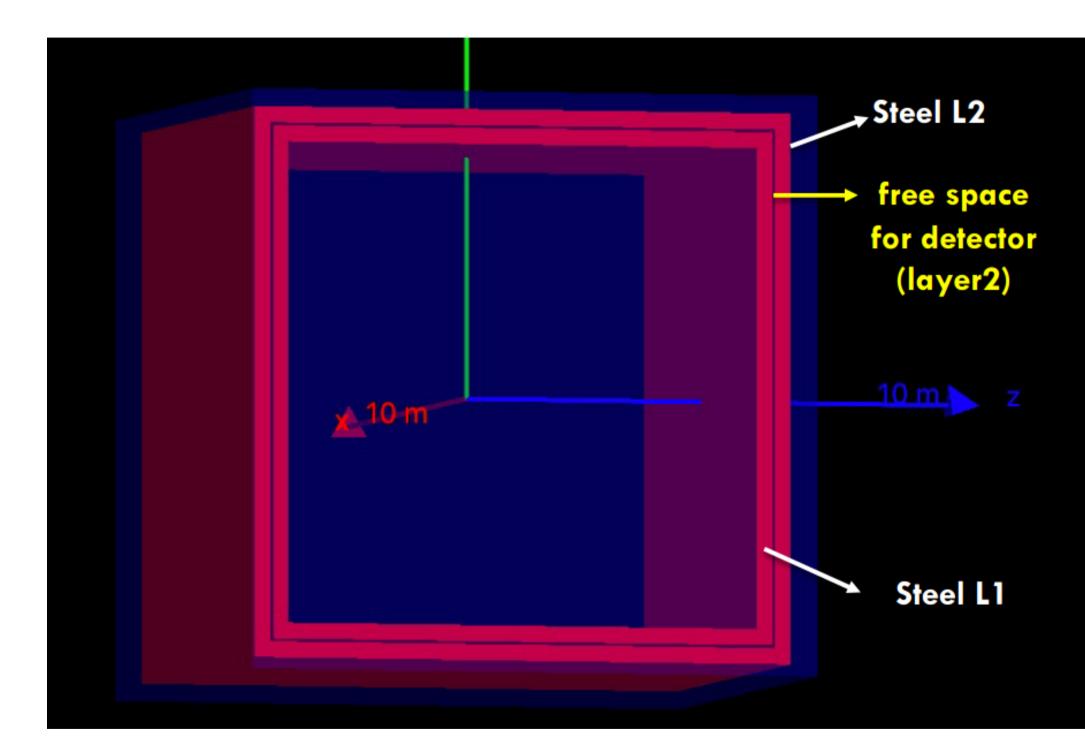
pitch = 1.5 mmFEE capacitance = 270 pF 5 million channels

# On going activities

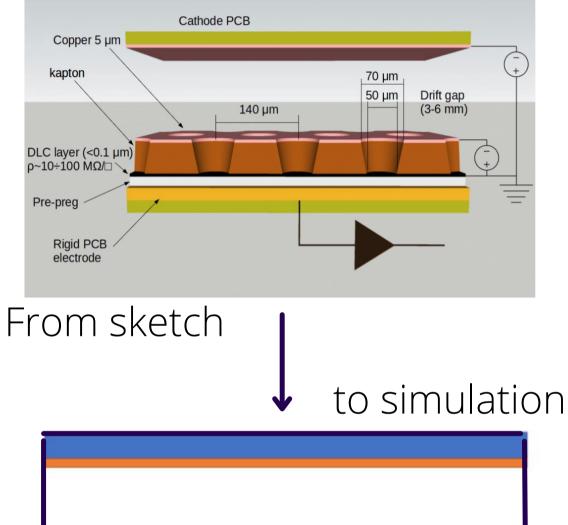




## Standalone Simulation of the muon detector



## To be inserted in official simulation. Endcap in preparation





### Different layers

## micro-RWELL parametrization in simulation

SIMULATION

DATA

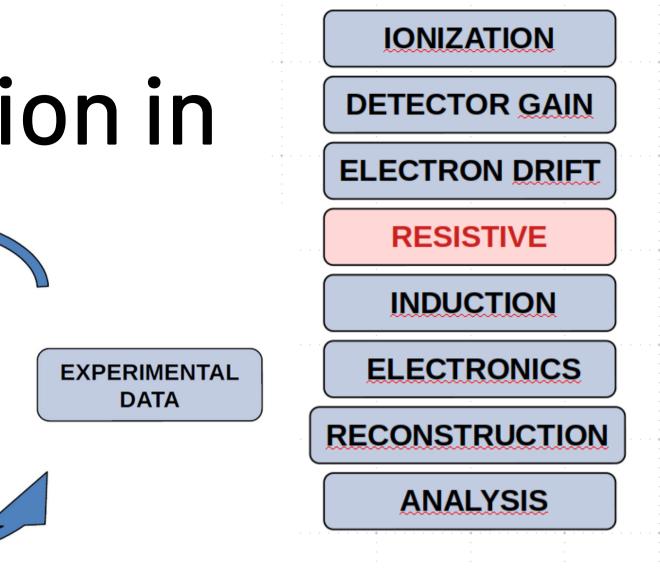
Use test beam data to tune the simulation

## Resistivity

Simulate the charge spread dispersion at the anode using approach of *NIM* A 566 (2006) 281-285

TUNING

Study the probability to induce a signal on neighbor strip as a function of - charge in the central strip - relative time delay



## Interstrip cross talk



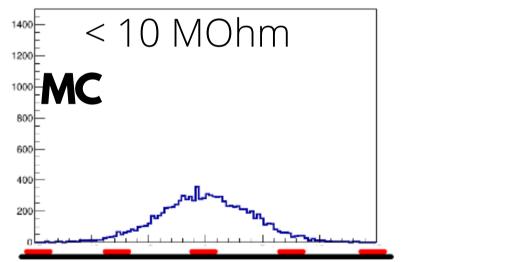
# Resistivity scan

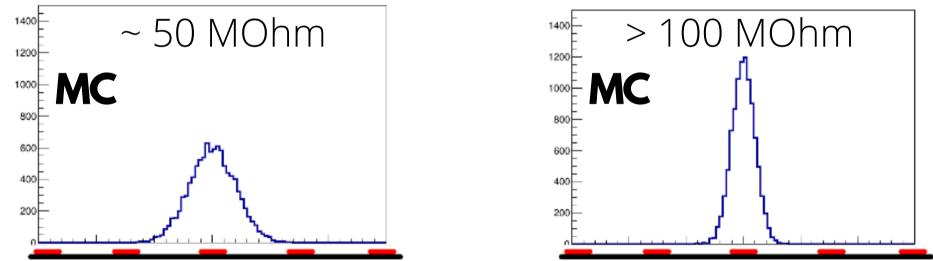


## R&D to identify optimal DLC resistivity by studying spatial performance

Preshower: 10, 30, 50, 70, > 100-200 M0hm/square Muon:15, 35 M0hm/square

## Effect of resistivity on charge spread

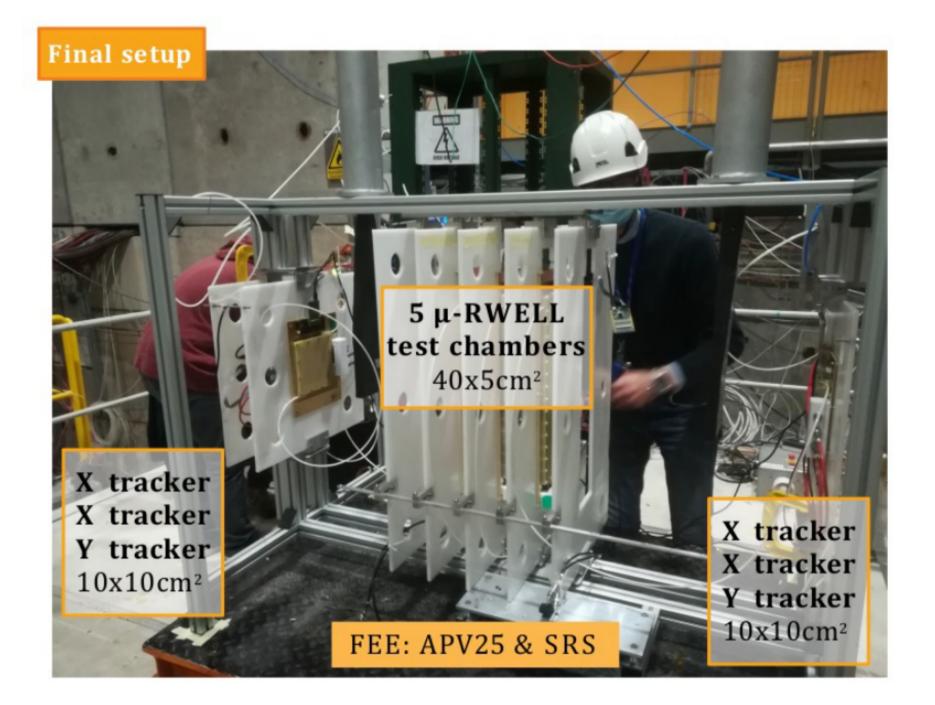






## Test beam performed in October 2021 at SPS-H8-CERN line

Instrumented  $5x40 \text{ cm}^2 1D$  micro-RWELL modules with SRS DAQ and APV readout to have a comparison with previous results



a) **Design optimization**: - different HV filter applied b) **Detector characterization** - HV scan at 0° - HV scan at different angles and drift field

140-180 GeV/c muon and pion beam Operated in  $Ar/CO_{2}/CF_{4}$  (45/15/40)

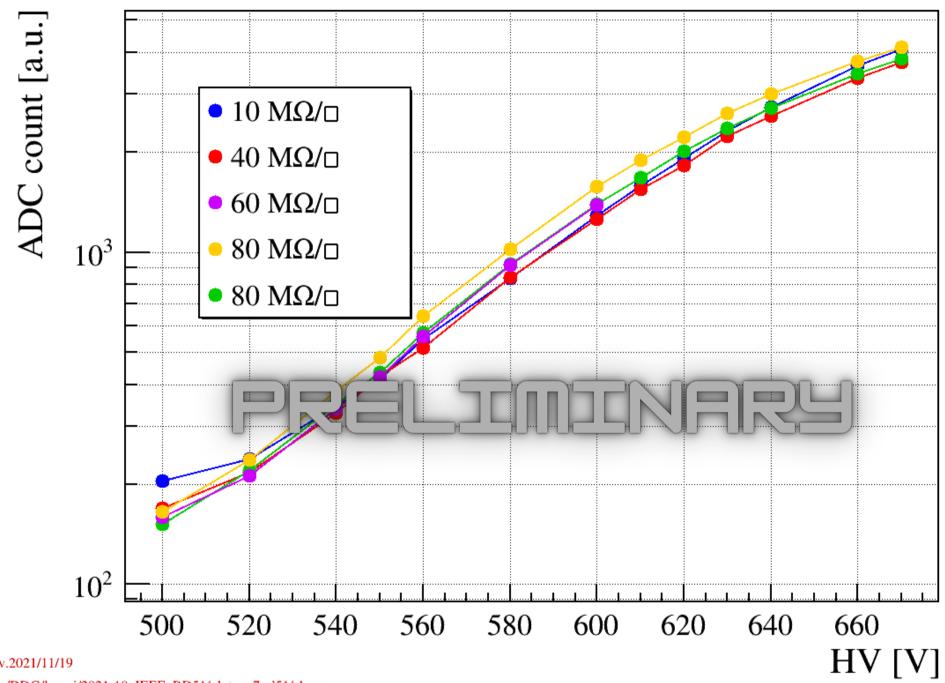


# Test beam

## **1- Signal shape**

(cluster charge, cluster size) 2 - **Detector performance** 

(efficiency, resolution)

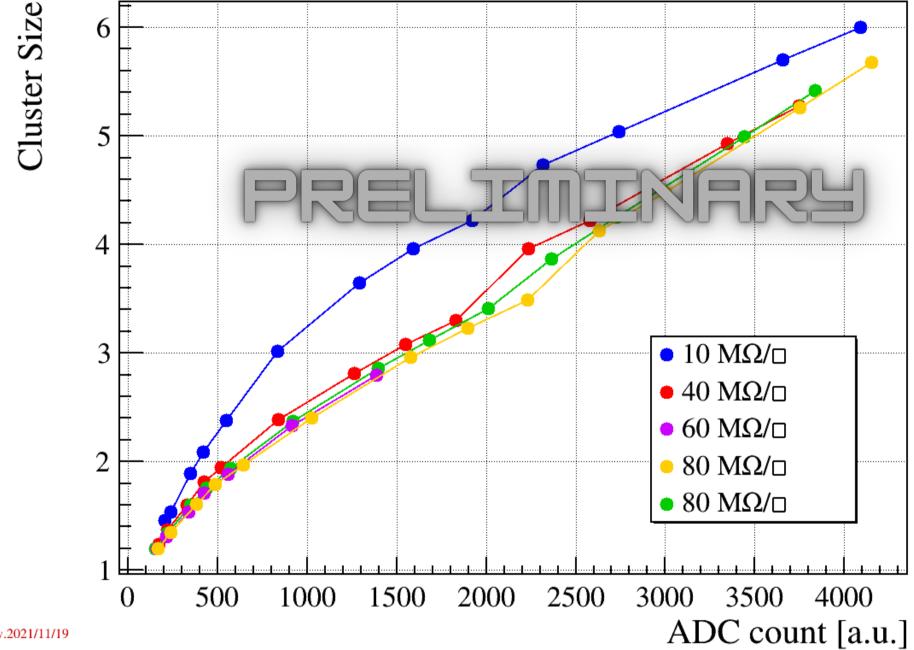


Ok, since the resistivity shall not influence the gain, that depends mostly on HV settings

~/DDG/lavori/2021-10\_IEEE\_RD51/plot wg7 rd51/charge

## HV scan

## Similar behaviour for all the prototypes





10 MOhm/square chamber has larger cluster size even with smaller HV settings

Other shows common behavior. No prototypes above 100 MOhm/square due to material shortage

## Cluster size

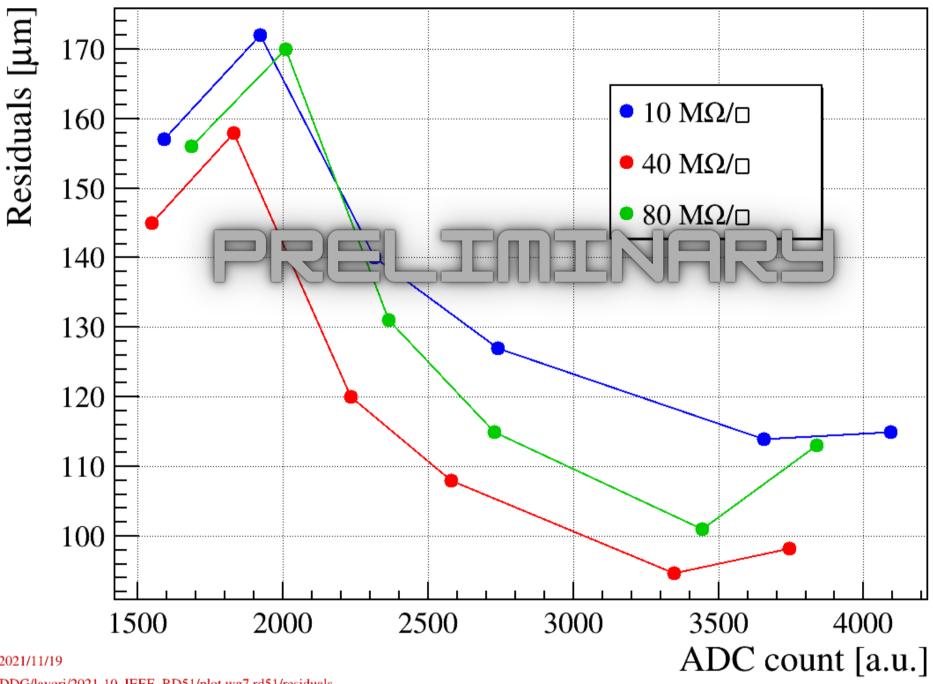
<sup>-/</sup>DDG/lavori/2021-10\_IEEE\_RD51/plot wg7 rd51/clussize

# Residual distribution

Residual shrinks with increasing HV settings

The best resolution is for intermediate resistivity: 40 MOhms/square better than the others

No Alignment and tracking contribution not subtracted



v.2021/11/19 ~/DDG/lavori/2021-10\_IEEE\_RD51/plot wg7 rd51/residuals

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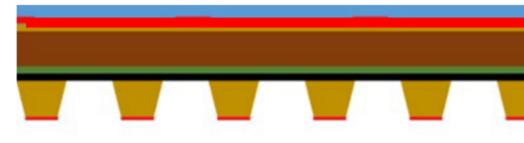
# 2D readout R&D ideas

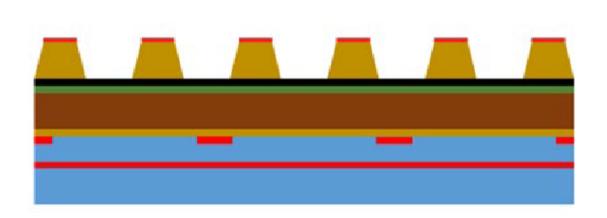
### micro-RWELL with 2D anode readout 21D micro-RWELL stacked

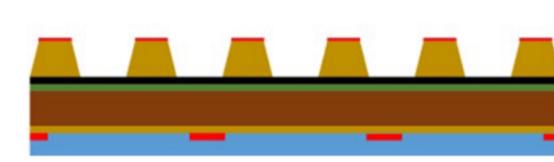
Good performance but need higher gain wrt to 1D micro-RWELL

More complex PCB construction

1 view per micro-RWELL easy PCB construction 2D performance to be measured







### micro-RWELL with strips on top and anode

HV on DLC, TOP to ground

2D performance to be measured



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## Preparation

DLC sputtering with new INFN-CERN machine @ CERN

## Step 1: producing u-RWELL\_PCB (1D $10x10 \text{ cm}^2$ )

- with top patterned (pad/strip)
- without bottom patterned

## Step 2: DLC patterning

- in ELTOS with BRUSHING-machine

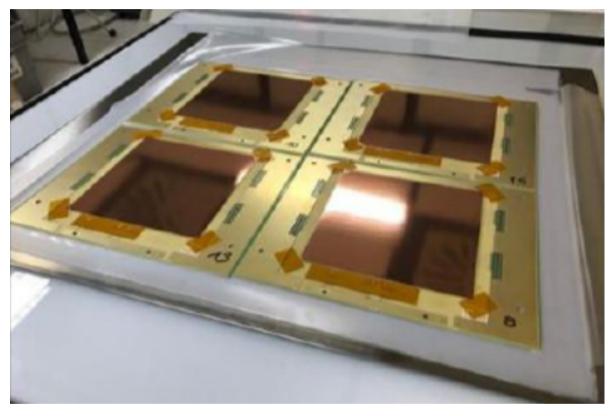
## Step 3: DLC foil gluing on PCB

- double 106-prepreg (~2x50 um thick) (already used in ELTOS)
- pre-smoothing + 106-prepreg (~50 um thick)
- single 1080-prepreg (~75 um thick)

## Step 4: top copper patterning

Step 5: Kapton etching on small PCB





## **Finalization**

Detector @ CERN for final preparation





### Table 2

Measured performance of the TIGER ASIC.

Parameters	Values
Input charge	5-55 fC
TDC resolution	30 ps RMS
Time-walk (5-55 fC range)	12 ns
Average gain	10.75 mV/fC
Nonlinearity (5-55 fC range)	0.5%
RMS gain dispersion	3.5%
Noise floor (ENC)	1500 e <sup>-</sup>
Noise slope	10 <i>e</i> <sup>-</sup> /pF
Maximum power consumption	12 mW/ch

# Test with TIGER ASIC Developed for BESIII CGEM-IT

Prepare new readout card based on System On Modules (SOM)

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## Summary and outlook Plenty of activities on-going

Contribution to full detector simulation to perform more detailed physics case studies

More results from 2021 test beam coming soon

Another test beam is planned to continue the 2D prototype characterization

Test of the TIGER ASIC with micro-RWELL prototype

Continue partnership with ELTOS (preparation) and CERN (finalization) to complete technology transfer

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### Working group:

A. Amoroso, I. Balossino, G. Bencivenni, V. Cafaro, G. Cibinetto, E. De Lucia, D. Domenici, R. Farinelli,G. Felici, I. Garzia, M. Gatta, P. Giacomelli, M. Giovannetti, S. Gramigna, L. Lavezzi, M. Melchiorri, GM,G. Morello, G. Papalino, M. Poli Lener, M. Scodeggio, S. Sosio

Selected bibliography	01 02 03	JINST Nucl.II
	04 05	JINST
TE CINEN CINEN	06	Eur.Pł

T 10 (2015) 02, P02008

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Instrum.Meth.A 924 (2019) 181-186

T 15 (2020) 09, C09034

T 16 (2021) 08, P08036

Phys.J.Plus 136 (2021) 11, 1143

New Document - Writepad



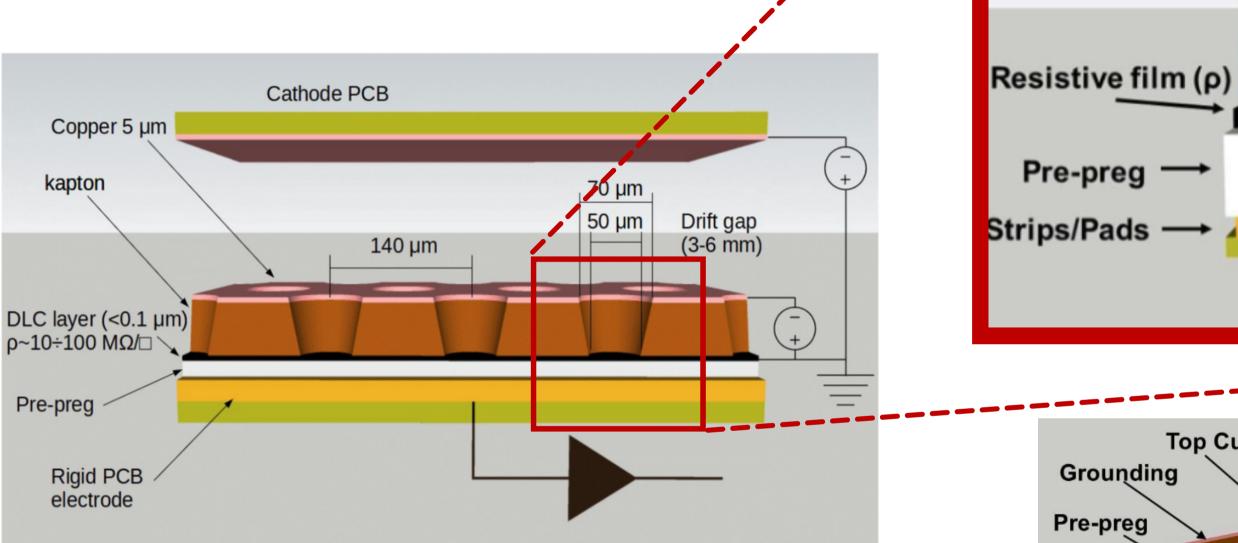
File Edit Format View Help

# Additional

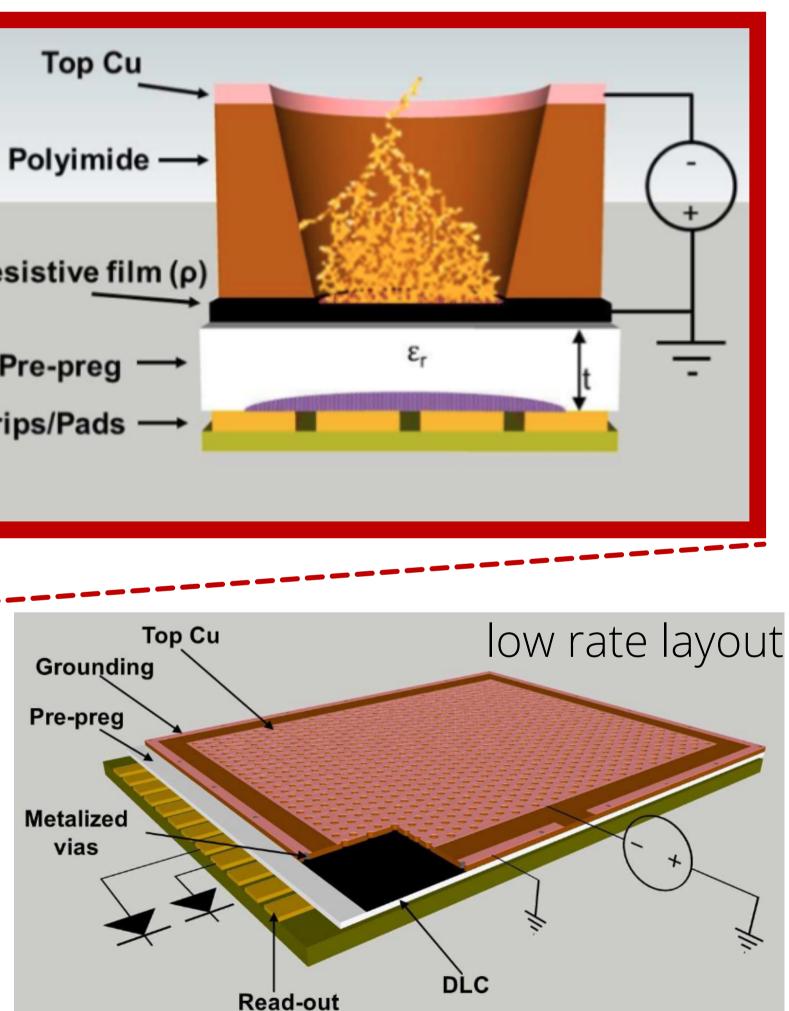
# material

# micro-RWELL

### A SHORT INTRODUCTION



Single stage resistive Micro Pattern Gas Detector firstly designed by G. Bencivenni in 2007

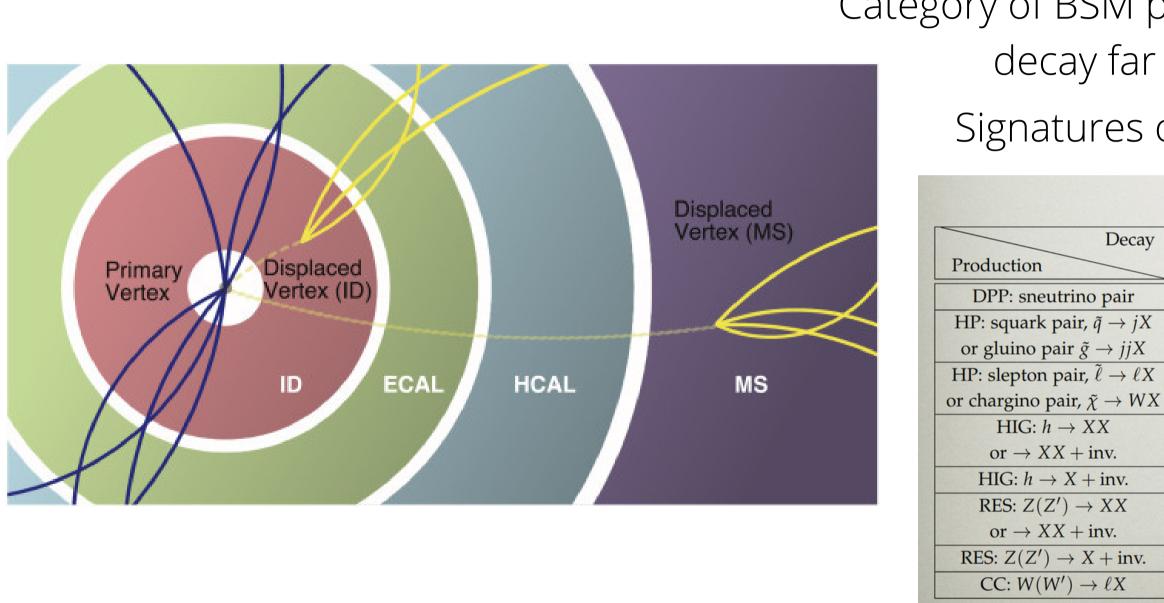


Top Cu

Metalized

vias

Long Lived Particles (LLP)



https://indico.cern.ch/event/714087/contributions/2985914/attachments/1650488/2641192/LHC-LLP\_Shuve.pdf

Muon detector with high spatial resolution can be used to measure very long displaced vertexes!

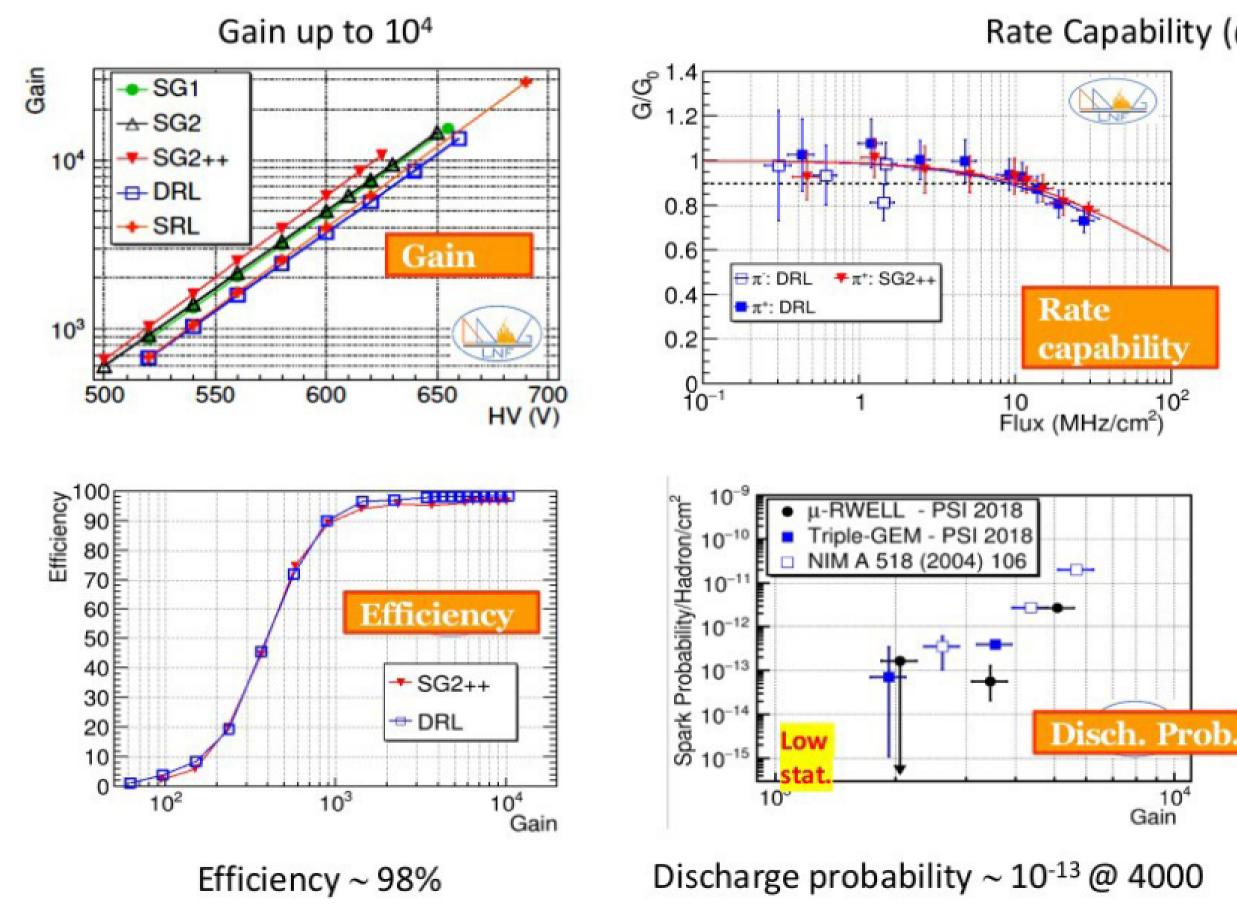
## Category of BSM particles that, due to feeble interaction, decay far away from the primary vertex

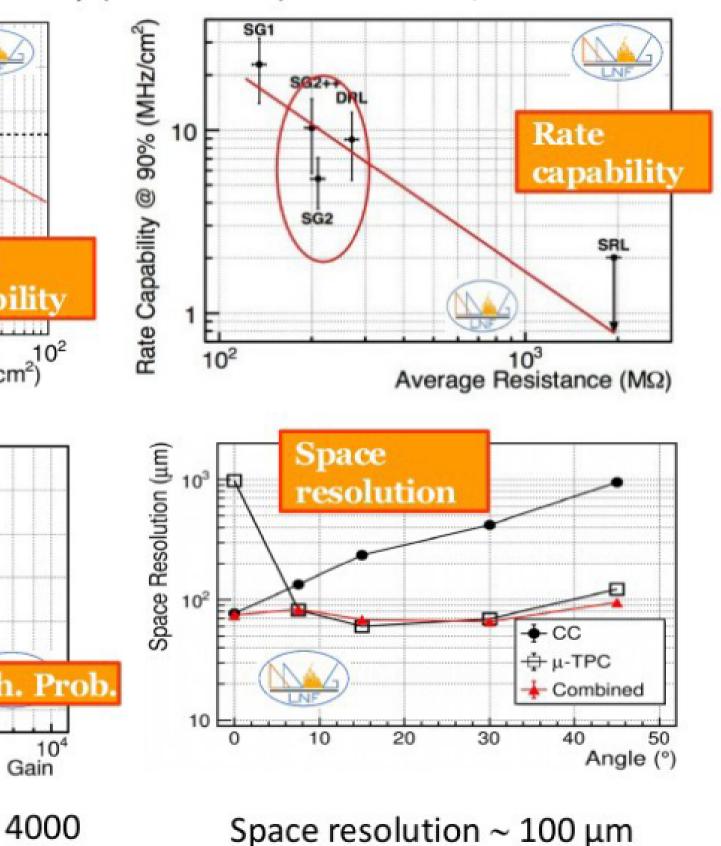
Signatures of different BSM models similar

×	$\gamma\gamma(+ ext{inv.})$	$\gamma + { m inv.}$	jj(+inv.)	jjℓ	$\ell^+\ell^-(+inv.)$	$\ell^+_{\alpha}\ell^{\beta\neq\alpha}(+\text{inv.})$
	+	SUSY	SUSY	USY SUSY SUSY		SUSY
	+	SUSY SUS		SUSY	SUSY	SUSY
K X	+	SUSY	SUSY	SUSY	SUSY	SUSY
	Higgs, DM*	+	Higgs, DM*	RHν	Higgs, DM* RHν*	RHv*
	DM*, RHv	+	DM*	RHν	DM*	+
	Z', DM*	+	Z', DM*	RΗν	Z', DM*	+
	DM	+	DM	RHν	DM	+
	+	† † RHν*		RHν	RHv*	RHv*

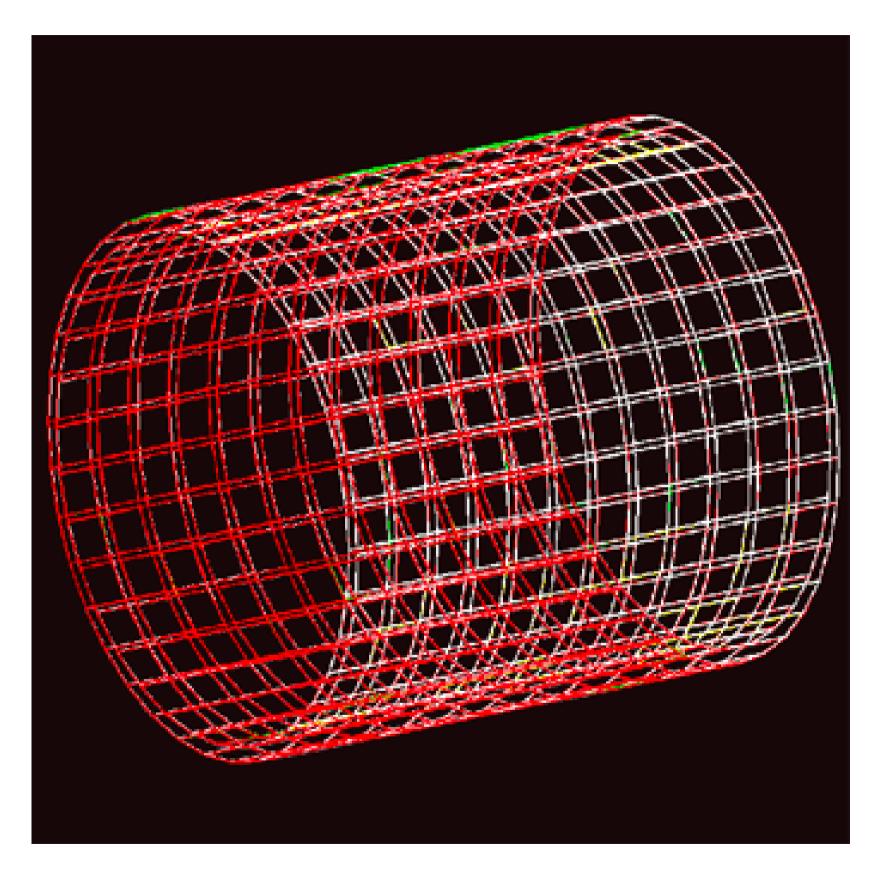
### neutral LLP channels

## **µ-RWELL performance overview**





Rate Capability (@ G= 5000) ~ 5-10 MHz/cm<sup>2</sup>



**Barrel Preshower layout** 

Optimization on-going on reducing input strip capacitance

Few Options:

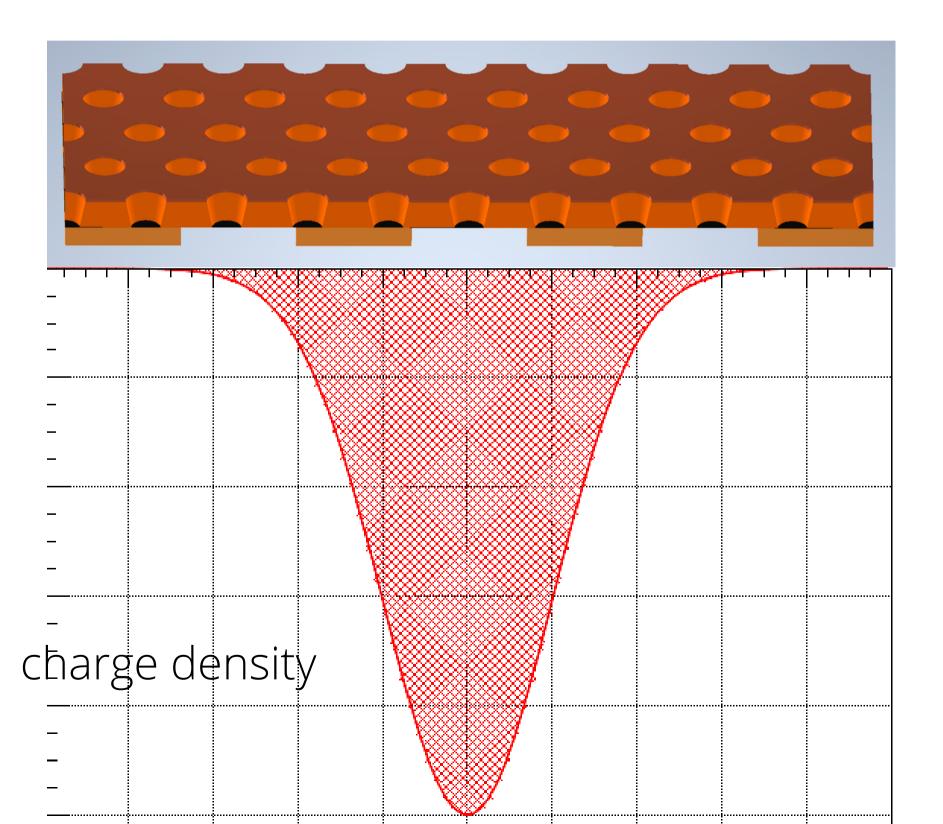
- pitch to 1-1.2mm but an increasing number of channels -> to keep low-cost necessary TIGER ASIC

- narrower strips but to understand the charge collection -> to see signals low threshold TIGER ASIC

## **GEANT4** Simulation by E. Fontanesi, PhD

## **Muon** detector similar, but larger

## The spread of the charge on the resistive layer has been described by M. S. Dixit, A. Rankin, NIM A 518 (2004) 721-727, NIM A 566 (2006) 281-285



$$ho\left(x,y,t
ight)$$
 =

$$\sigma(x,t) = \frac{q}{\sqrt{2\pi} \left[\sigma_0 \left(1 + \frac{t-t_0}{\tau}\right)\right]} exp\left[-\frac{\left(x-x_0\right)^2}{2\sigma_0^2 \left(1 + \frac{t-t_0}{\tau}\right)^2}\right] \Theta(t-t_0)$$

- q the charge produced in an avalanche - x0 the position of the primary electron entering the amplification stage -  $\sigma$ 0 a theoretical charge space extension of the avalanche - t0 the starting time of the track - τ the decay time of the charge density due to the electrons movement towards the ground on the resistive surface.

 $\tau$  is the parameter to be tuned

 $= \frac{Nq_e}{2\pi (2ht + w^2)} exp\left[-\left(x^2 + y^2\right) / \left(2\left(2ht + w^2\right)\right)\right]$ 

# TB full dataset

Optimization S/N vs HV resistor filter 、

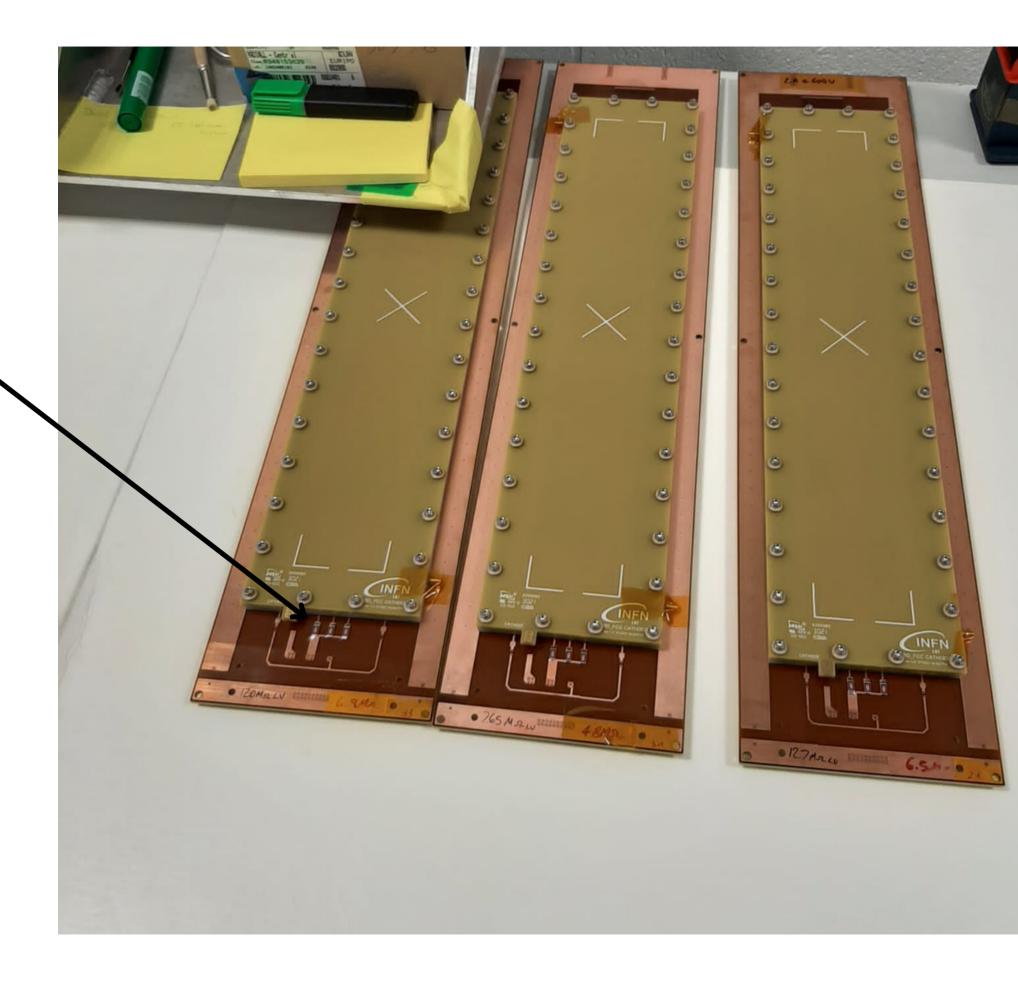
HV scan  $0^{\circ}$  - for trackers & test chambers

HV Scan 40° for test chambers

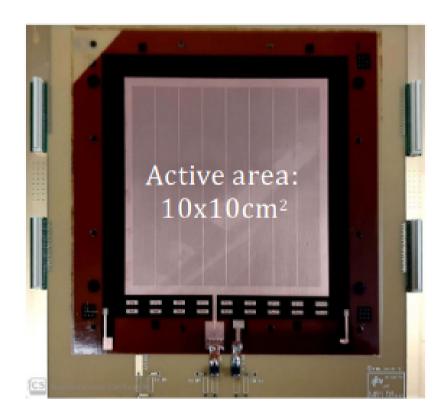
Angle scan [0,10,20,30,40]° test chambers

Drift filed 0.5 kV, HV and angle scan

Drift field scan 0°



## **Detector Comparison**





### µ-RWELL trackers

 $10 x 10 cm^2$ 

300µm / 400µm / 10cm

100µm

Standard (70µm)

 $30 \div 40 M\Omega / \Box$ 

Active area

Strip width/pitch/lenght

Strip distance from DLC

Amplification WELL diameter

DLC surface resistivity

μ-RWELL test	FEE signal
5x40cm <sup>2</sup>	
150µm / 400µm / 40cm	÷ 2
50µm	× 2
Larger (to be measured)	÷ ?
10÷80MΩ/□	



## Capacitive-sharing readout: Principe & Motivation (K.GNAVO)

### Principe of capacitive-sharing readout structures:

- Vertical stack of pads layers ⇒ Transfer of charge from MPGD via **capacitive coupling** \*
- A given arrangement of the pads position from one layer to the layer underneath as well \* as the doubling in size of the pad pitch allows:
  - Transverse sharing of the charges between neighboring pads of the layer (i+1) \* from vertical charged transfer from layer (i) through capacitive coupling
  - Principle of transverse charge-sharing through capacitive coupling i.e., ÷ capacitive- sharing is illustrated on the cross-section sketch on the left
- The scheme preserves of the position information i.e. spatial resolution with large readout strips or pads: Goal 50  $\mu$ m for 1-mm strip r/o and 150  $\mu$ m for 1 cm<sup>2</sup> pad r/o
- Basic proof of concept established with 800 µm X-Y strip

### Motivation & some key facts of capacitive-sharing readout:

- Develop high performance & low channel count readout structures for MPGDs:
- Reduce the number of readout electronic channels for large area MPGDs \*
- Low-cost technology for large area 2 standard PCB fabrication techniques \*

Initial electron clouds size from triple-GEM will hit on average 2 to 3 pads of .6125 mm

50 µm Kapton

50 µm Kapton

50 µm Kapton

50 µm Kapton





### Cross section of capacitive-sharing pad readout with 6.4 mm × 6.4 mm pads

DLC layer to evacuate charges to the ground

foil	anode layer with pad size = $0.3 \text{ mm}$
foil	transfer layer with pad size = $0.6 \text{ mm}$
foil	transfer layer with pad size = 1.2 mm
foil	transfer layer with pad size = $3.2 \text{ mm}$
	Readout layer with pad size = 6.4 mm

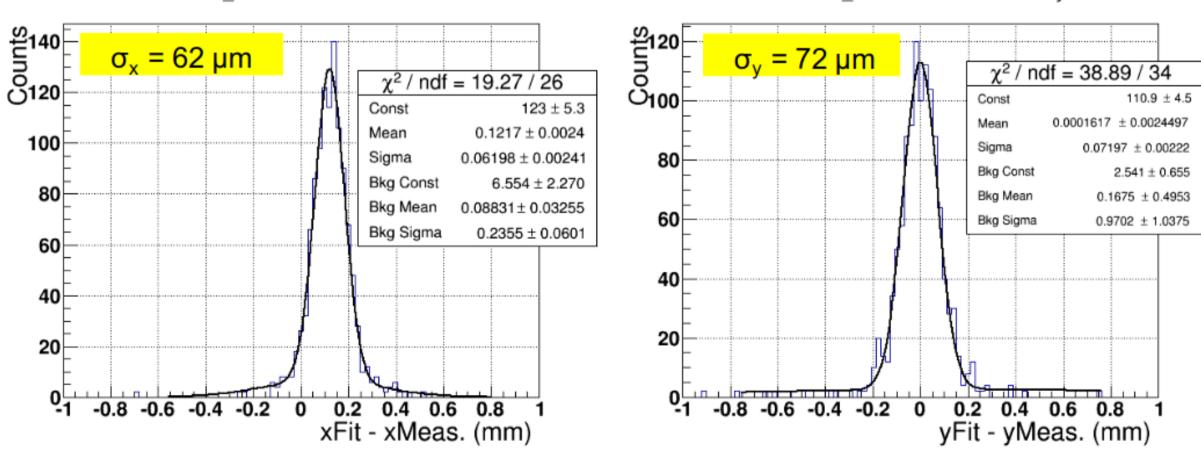
Top view of two pad-sharing layers						
Pad <sub>k-1</sub> on layer <sub>i+1</sub>		pad <sub>k</sub> on layer <sub>i+1</sub>			Pad <sub>k+1</sub> on layer <sub>i+1</sub>	
	pad <sub>j-1</sub> o	n layer <sub>i</sub>	pad <sub>j</sub> on <u>layer</u> i	pad <sub>j+1</sub>	on layer <sub>i</sub>	



## Capacitive-sharing X-Y strip readout: µRWELL prototype

10 cm  $\times$  10 cm  $\mu RWELL$  with capacitive-sharing 2D strip readout

- ♦ Pitch is 800 µm → twice COMPASS readout strip design
- ✤ X-strip and Y-strips on two separate layers with No connecting vias → Easy fabrication for large area, low-mass capability
- Strip parameters: top strip (y-strips) = 250 μm, bot strip (x-strips): 750 um × 500 μm -> require tuning for equal charge sharing
  - Top and bottom strip area overlap minimized by design to minimize cross talk and capacitance etc ...
- 3 capacitive-sharing pad layers with: 200 μm, 400 μm and 800 μm pad size respectively
- Tested in electron beam in Hall D @ JLab (Sept-Oct 2021)



CAPASTRIP\_URWELL: Residuals on x-axis

CAPASTRIP\_URWELL: Residuals on y-axis

RD51 Collaboration Meeting, 11/17/2021



arge area, low-mass capability uire tuning for equal charge sharing acitance etc ...



